

## FACT SHEET

# ICT-FSL-K4

Under Development

4 THERMALLY CONDUCTIVE GAP FILLERS, PADS, SPACERS, SOFT-, ULTRASOFT-GEL



## DESCRIPTION

ICT-FSL-K4 is currently still in the final phase of prototype status.

In the near future, in addition to the FSL-F3 and the FSL-D gap filler spacer, which has already been very successfully placed on the market another best product performer in price and quality will be available to the user.

## TYPICAL PROPERTIES

Operating temperature	from -60 to 180 °C
Thermally conductive	Yes
Thermal conductivity	2 W/m <sup>2</sup> K
Density	2.5 g/cm <sup>3</sup>
Color	Light Blue
Dielectric breakdown voltage	10.00 kV/mm
Electrically conductive	No
Hardness (Shore 00)	42

## FEATURES

- › Very good thermal conductivity 2 W/m<sup>2</sup>K
- › Low heat transfer resistance 0.42C°/W (1mm)
- › High dielectric strength > 10 KV /AC (1mm)
- › Very high elasticity and flexibility
- › Excellent mechanical damping properties
- › Non-flammable according to UL 94 VO
- › One-sided self-adhesive (AV) or double-sided self-adhesive.

## DELIVERY FORMS / APPLICATIONS

Under development

ICT4TIM Partners



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